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|-----|---------|--|---|----|----|------------------|
| L12 | 1909357 | (top upper front) near (side or surface) or topside or upperside frontside | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/13 13:05 |
| L13 | 2052185 | (top upper front active) near (side or surface) or topside or upperside frontside activeside | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/13 13:06 |
| L14 | 167534 | 11 with 13 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/13 13:10 |
| L15 | 312902 | 11 with 3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/13 13:10 |
| L16 | 829170 | mosfet mos adj fet fet transistor | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/13 13:11 |
| L17 | 2355 | 14 same 15 same 16 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/13 14:11 |
| L18 | 79 | 14 same 15 same 16 same 6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/13 13:15 |
| L20 | 36 | 18 and (@ad < "19991216") | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/13 14:13 |

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|---------|---|---|------------------|---------|------------------|
| L3 | 3819830 | (back or under or below) near (side or surface) or backside or underneath or bottom | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/13 13:04 |
| L4 | 12523 | through adj (wafer chip) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/13 12:57 |
| L6 | 597215 | through adj hole throughhole through adj hole | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/13 13:03 |
| L7 | 183380 | mosfet mos adj fet fet | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/13 13:10 |
| L8 | 4616 | 6 and 7 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/13 13:04 |
| L9 | 779 | 6 same 7 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/13 13:04 |
| L10 | 384 | 6 with 7 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/13 13:04 |
| L11 | 6351384 | terminal electrode source drain gate | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/13 13:04 |

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|-----|---------|--|---|----|-----|------------------|
| L21 | 239 | 14 same 15 same 16 near2 (power) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/13 14:11 |
| L22 | 98 | 21 and (@ad < "19991216") | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/13 14:21 |
| L23 | 707433 | (chip or die or dice or ic) | US-PGPUB; USPAT | OR | ON | 2005/05/13 14:13 |
| L24 | 4722000 | electrode or contact or pad | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/13 14:13 |
| L25 | 57 | (encapsulat\$6 epoxy resin housing packaging)near2 (window or opening or hole) same expos\$4 near2 L24 same L23 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/13 14:14 |
| L26 | 4297766 | (encapsulat\$6 epoxy resin housing packaging) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/13 14:18 |
| L27 | 47 | 21 and (@ad < "19991216") and 26 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/13 15:20 |
| L29 | 2761 | ((438/111) or (438/112) or (438/116) or (438/123) or (438/124) or (438/64)).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/05/13 15:20 |
| L30 | 1177 | 29 and (@ad < "19991216") | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/13 15:20 |